



Docket No. MAIKP131US

IT601US

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Re **PATENT** application of:

Applicant: Teng-Wang Huang et al.  
Application No.: 10/814,570  
For: PROCESS FOR ETCHING A SUBSTRATE  
Filing Date: March 31, 2004  
Examiner: Duy-Vu Nguyen Deo  
Art Unit: 1765

**REPLY TO OFFICE ACTION DATED DECEMBER 7, 2005**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir or Madam:

Favorable reconsideration of the above-identified application is respectfully requested in view of the following amendments and remarks.